

# **AN-1376 External Serial Interface Reduces Simultaneous Switching Output Noise in FPGAs**

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## **ABSTRACT**

This application report highlights how using external SerDes in conjunction with minimum current drive FPGA I/O can reduce FPGA’s internal noise and reap the benefits of a serial interface across the system. This may allow designers to use low end FPGAs with external SerDes to reduce cost and still have high analog performance.

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## 1 Introduction

A critical issue with any FPGA (Field Programmable Gate Array) design is Simultaneous Switching Output (SSO) noise. SSO noise, also known as ground bounce, is a result of large instantaneous changes in current across the power/ground inductance of the integrated circuit. This potential problem becomes more and more serious as the number of active high-drive LVCMOS outputs on a FPGA design increases. In large FPGAs with several synchronous parallel interfaces this phenomenon can result in poor system performance or intermittent data errors.

The FPGA SSO noise is minimized by using the lowest drive current from the FPGA and reduces the parallel bus to a single differential signal. LVCMOS outputs from the FPGA are unsuited for driving over long interconnects or at high data rates. Upgrading the parallel interfaces with an external Serializer/Deserializer (SerDes) interface to the FPGA will reduce SSO noise and improve the overall system performance. The close proximity of the external SerDes to the FPGA allows the FPGA I/O to be programmed at the minimum CMOS drive level of about 2 mA. Reducing the drive level lowers the dynamic currents within the FPGA curbing the generation of SSO noise. Noise generated in the I/Os on a FPGA can corrupt the analog performance of FPGA PLLs or other system analog resources.

The Altera Cyclone or Xilinx Spartan are good examples of economical FPGAs intended for low to medium end applications. They do not contain dedicated serialization or deserialization circuitry for high-speed communications limiting the maximum data rate. This makes the Cyclone and Spartan good candidates for an external serial interface. Using a SerDes external to an FPGA allows an entire multi-byte parallel interface to be condensed to one or more high-speed signal pairs for economical transmission across system interfaces. Before and after measurements of the SSO noise on a Cyclone FPGA will help to quantify the improvements made by the change in the FPGA programmed I/O current drive.

## 2 Test Setup for Simultaneous Switching Output Noise

The FPGA/SerDes evaluation test setup is shown in Figure 1.

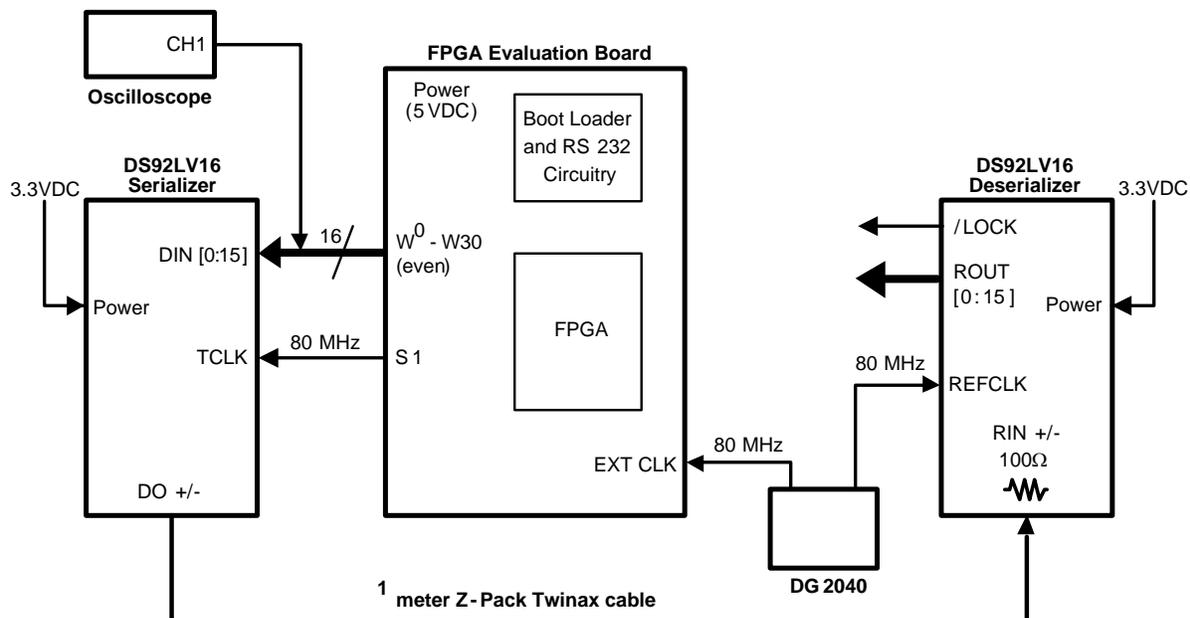


Figure 1. DS92LV16 SerDes and Cyclone FPGA Test Setup

### 2.1 Test Setup Schematic

Figure 2 shows an example of a system implementation using the Cyclone and DS92LV16. The specific Cyclone I/Os used for the interface would depend upon the device selected, additional required functionality, and other layout constraints. For the best and most consistent AC performance, all the FPGA—SerDes interconnects should be selected from a single I/O bank.

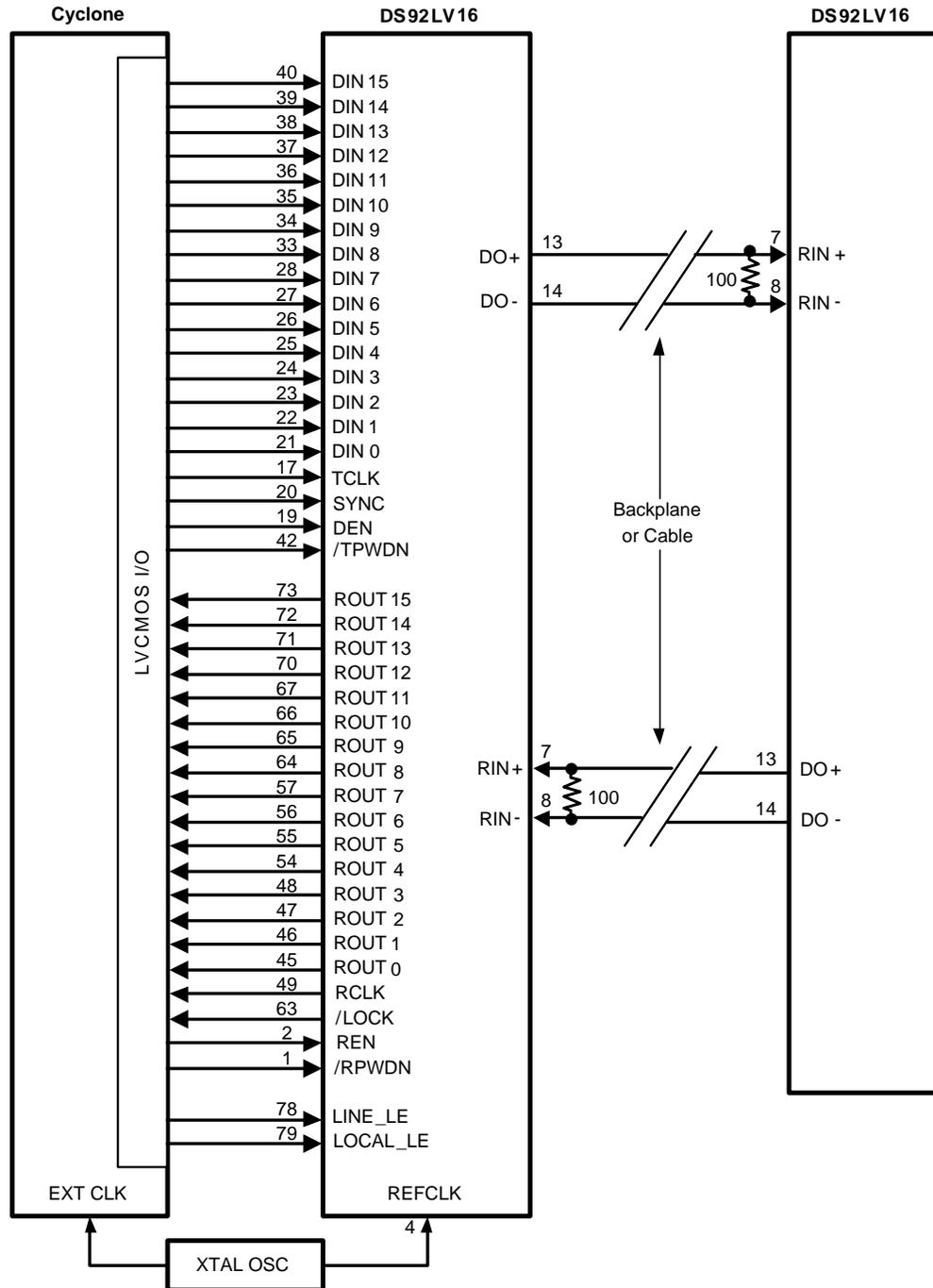


Figure 2. Cyclone and DS92LV16 Connections

## 2.2 Component Information

### 2.2.1 DS92LV16 SerDes

Figure 3 shows the block diagram for the DS92LV16 SerDes. The serializer takes 16-bits of parallel LVCMOS data and translates it into a serial stream with embedded clock. The serial data stream is output as a Low Voltage Differential Signaling (LVDS) signal with a maximum speed of 1.44 Gbps across cables or backplanes.

The deserializer takes the differential LVDS signal and translates it back into 16-bit parallel LVCMOS data. The device also contains loop back test capability for testing line and local interfaces. The Serializer and Deserializer operate independently with separate clock, enable, and power down pins.

### 2.2.2 Altera Cyclone FPGA

Table 1 shows the Cyclone device family and features. After selecting an FPGA to handle the logic and processing requirements of the application, the designer may choose to add an external SerDes due to system interface requirements. The FPGA choice depends on the end application requirements; the DS92LV16 can be effectively used with any FPGA density or architecture.

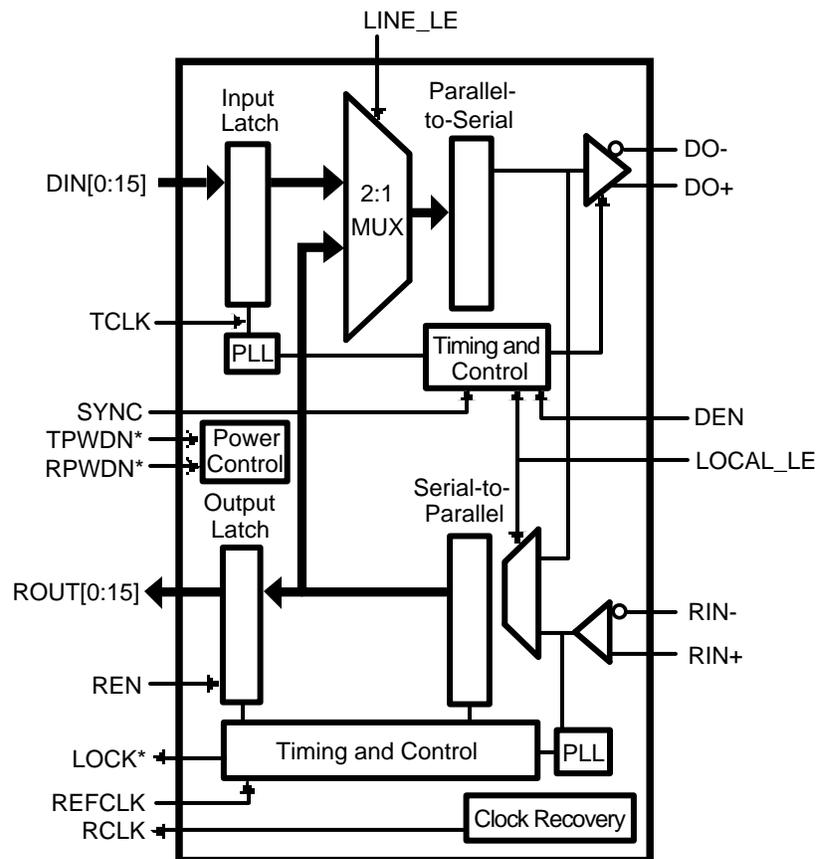


Figure 3. DS92LV16 Block Diagram

Table 1. Device Features

Feature	EP1C3	EP1C4	EP1C6	EP1C12	EP1C20
LEs	2,910	4,000	5,980	12,060	20,060
M4K RAM Blocks (128 × 36 bits)	13	17	20	52	64
Total RAM Bits	59,904	78,336	92,160	239,616	294,912
PLLs	1	2	2	2	2
Maximum User I/O Pins	104	301	185	249	301

### 3 Simultaneous Switching Output Noise

SSO noise, as the name implies, is the result of internal and external circuitry switching at the same time. The cumulative effect of all this switching current passing through power and ground inductance is device-generated noise. This noise is visible on non-switching outputs as internal movement in the ground or power network.

The following test was conducted with the FPGA to DS92LV16 parallel bus clocking at 80 MHz and the LVCMOS output drive current of the FPGA set to either 24 mA or 2 mA. This will allow for the observation of SSO noise and other noise related effects on the parallel bus.

1. Simultaneous Switching Outputs—Switched 16 FPGA outputs simultaneously while monitoring a “quiet output” for ground bounce on the FPGA evaluation board.
2. Clock Output Jitter—Switched 16 FPGA outputs simultaneously while monitoring a FPGA clock output for jitter.

Figure 4 shows the level of noise that can result from only 16 LVCMOS I/Os switching at the same time.

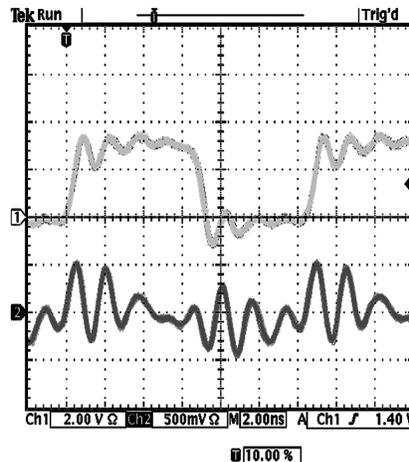
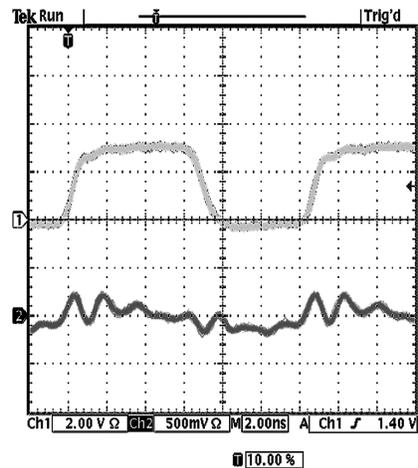


Figure 4. Active Output Transitions and “Quiet Output” (bottom), SS Data, 24 mA

The upper waveform (CH1) is the active switching transition repeated on 15 additional LVCMOS FPGA outputs driven at 24 mA. There is a visible 600 mV undershoot present just after the waveform falling edge. As expected, the bottom “quiet output” waveform (CH2) tends to follow this pattern highlighting an internal ground movement of  $\pm 500$  mV around the true board ground. This internal noise in the ground and power systems can dynamically alter the supply voltage of switching logic. The dynamic shift in supply voltage will cause changes in the switching characteristics of internal signals and reduce the performance of other more sensitive analog circuitry.

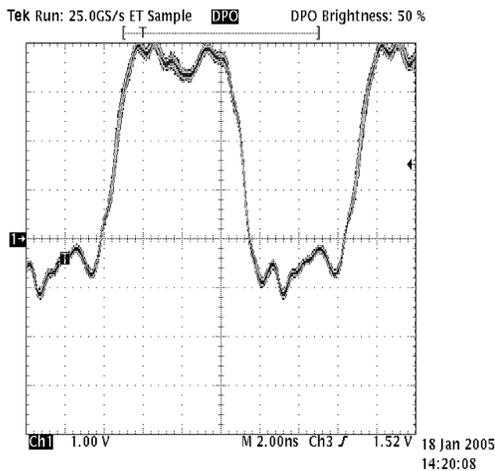
In addition, the output signal also shows ringing and undershoots.



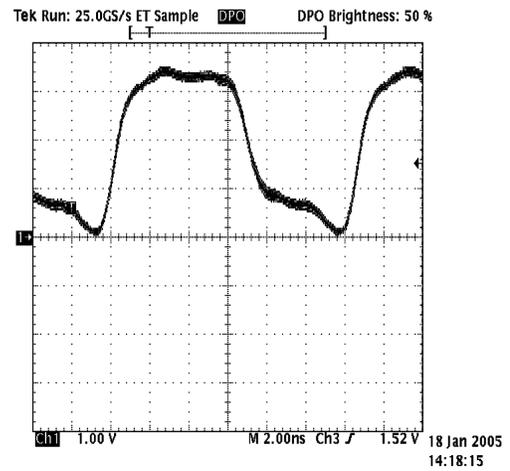
**Figure 5. Active Output Transitions and “Quiet Output” (bottom), SS Data, 2 mA**

Figure 5 shows the quiet and switching waveforms with the FPGA programmed for 2 mA (minimum) current drive. The upper waveform (CH1) is the active switching transition repeated on 15 additional LVCMOS FPGA outputs. Compared to the previous waveform, the 2 mA drive current results in slower transition times and greatly reduced undershoot relative to external ground. Monitoring the signal on a quiet output (CH2) shows the improvement on the internal ground as well.

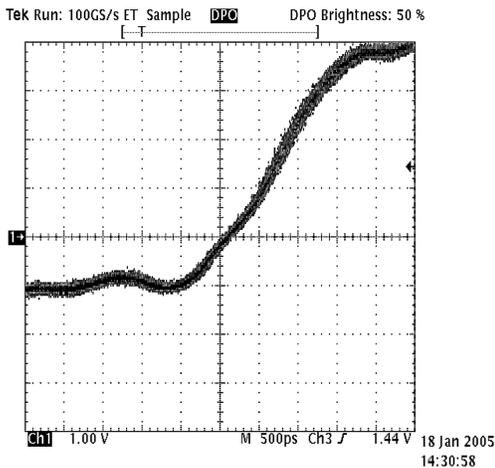
The FPGA drive current reduction improves the signal integrity and lowers the jitter of output Clock signals. The noise on the clock signal is another indication of diminished FPGA PLL analog performance. In addition to the reduction in FPGA performance, analog devices located adjacent to the FPGA will also be affected by the increase in ground noise. The following series of waveforms (Figure 6) show how a reduction in drive strength can improve the signal integrity and lower the jitter seen on FPGA output signals.



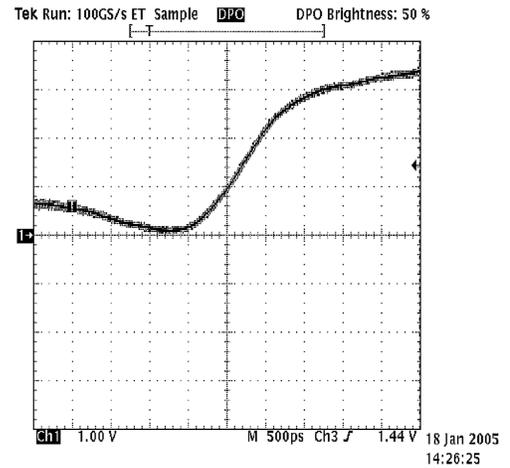
With 24 mA of drive programmed into the FPGA outputs, large excursions outside the supply rails are clearly visible.



Reducing the FPGA programmed drive to 2 mA results in a tightly controlled clock waveform.



Rising Edge Magnification: This view shows greater than 200 ps of clock jitter in the FPGA output that is a result of the increased drive current.

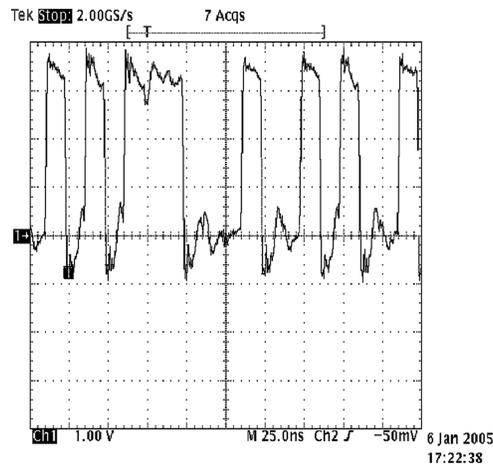


Rising Edge Magnification: This view shows how a reduced 2 mA drive current maintains good signal integrity and exceptionally low (~50 ps) jitter.

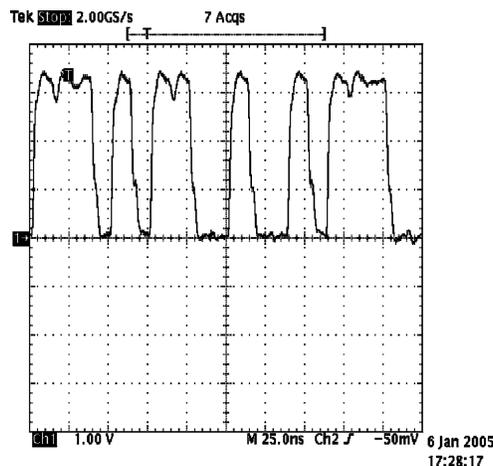
**Figure 6. 24 mA Drive vs 2 mA Drive for FPGA Output Clock Signal Integrity and Jitter**

The reduction in jitter will improve analog performance of adjacent components like the DS92LV16. Starting with a clean clock source means that significantly reduced jitter within the PLL bandwidth will allow for enhanced high-speed signal integrity.

By reducing the FPGA interconnect to short-to-point topology, the low drive (2 mA) setting can efficiently and cleanly drive the LVCMOS interconnect into the LVDS SerDes. Programming to the low drive setting reduces the noise generated by the FPGA and reduces system EMI. [Figure 7](#) and [Figure 8](#) clearly show undershoot and overshoot is completely eliminated and noise reduction achieved with low drive FPGA programming.



**Figure 7. 24 mA FPGA Output +4" Trace with PRBS Data**



**Figure 8. 2 mA FPGA Output +4" Trace with PRBS Data**

## 4 Benefits of Using External SerDes

LVC MOS outputs from the FPGA are unsuited for driving over long interconnects or at high data rates. To address these system demands and to reduce the number of signals at backplane or cable interfaces, SerDes devices with low voltage differential signaling (LVDS) technology are often employed.

### 4.1 External SerDes Reliability

The main function of any SerDes chipset is to translate data originating from a wide parallel bus into one or more serial bit streams and to convert the data back a wide parallel bus at the receiving end. With the system improvements SerDes devices bring, one of the first questions system designers may ask is how long the interconnect between the serializer and the deserializer can be that will still ensure error-free data transfer.

To find out the answers to questions of "How far?" and "How fast?" a type of testing called BER or Bit Error Rate Testing is done on the serial interface.

[Figure 9](#) shows the eye diagram at the DS92LV16 receiver after 1m of CAT5 cable. This diagram shows the wide open eye possible with inexpensive CAT5 cable running at a data rate of almost 1 Gbps. The maximum data rate of the DS92LV16 is approximately 1.5 Gbps.

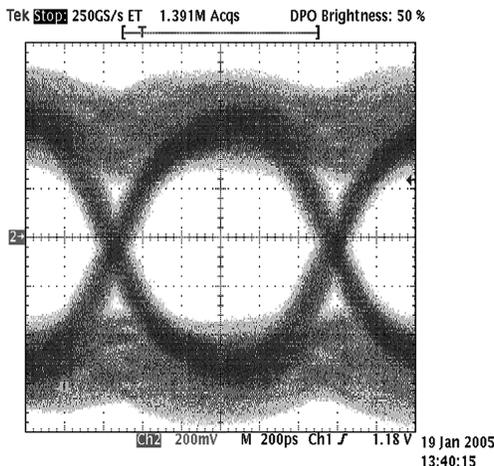


Figure 9. Eye Diagram after 1m of CAT5 Cable

A related example of this type of testing is shown below. As depicted in Figure 10, a BER transmitter provided 18-bit wide PRBS ( $2^{15}-1$ ) and a BER receiver received 18-bit wide PRBS ( $2^{15}-1$ ). The DS92LV18 transmitter serialized the sequence and sent it across a cable assembly; the DS92LV18 receiver then de-serialized the data, and sent the 18-bit wide PRBS pattern back to the BERT for analysis. Configuring the test setup in this manner allows the maximum operating frequency to be determined for each cable length. The maximum operating frequency of this system is defined as the maximum frequency of the device transmitter clock (TCLK) at which the device receiver misinterprets zero out of  $10^{12}$  data bits. This equates to the bit error rate of less than  $1 \times 10^{-12}$ . The test was conducted at room temperature and the power supply voltage for both devices was set to 3.3 volts. For a DS92LV18 SerDes the TCLK frequency equates to 1/20th of the high-speed serial data rate. For example, at the chipset maximum TCLK of 66MHz the serial data rate is running at a speed of 1.32Gbps.

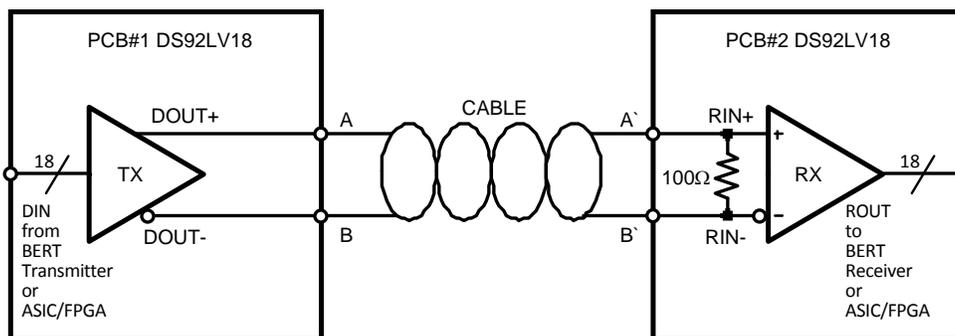


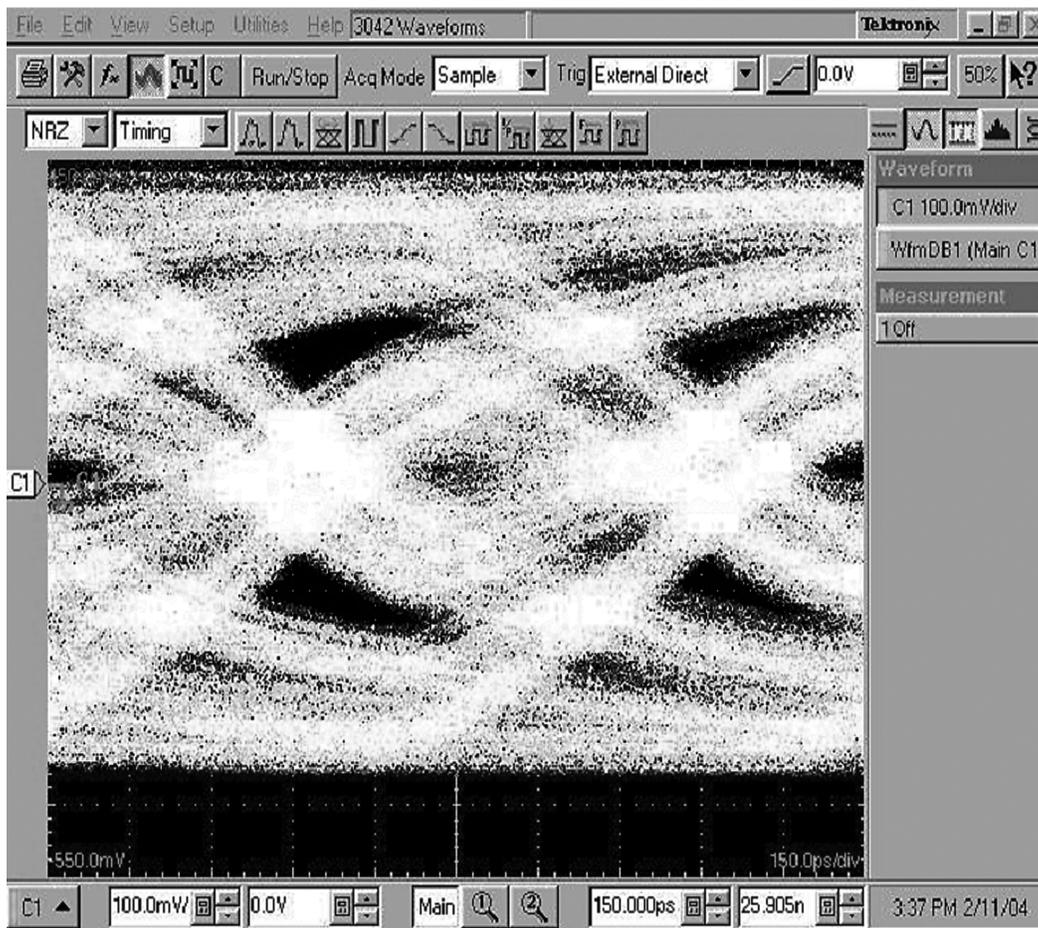
Figure 10. DS92LV18 SerDes BER Test Setup

Based on the BERT results, the DS92LV18 can be used in short to medium length cable interface applications. If employed to move data between two points across a generic category 5 cable, it can operate at its highest operating frequency (66 MHz) for cable lengths up to 10 feet. For lower operating frequencies, it can transmit error free data over cables longer than 50 feet. Shielded cables with lower nominal attenuation paired with connectors rated for gigabit operation enable you to make longer high-speed, error free connections.

Even though the speeds have increased dramatically, the serial interface can transfer data at a rate and distance just not possible with a parallel interface. In order to accommodate Gigabytes of data 32, 64, or even 128-bit parallel bus designs have been implemented. This resulted in massive routing bottlenecks at cable assemblies, memory board, and backplane interfaces. These performance-limiting issues were addressed when the parallel interfaces were replaced with one or more high-speed serial interfaces. This architecture shift has enabled system performance, packaging, and features that could not otherwise have been achieved.

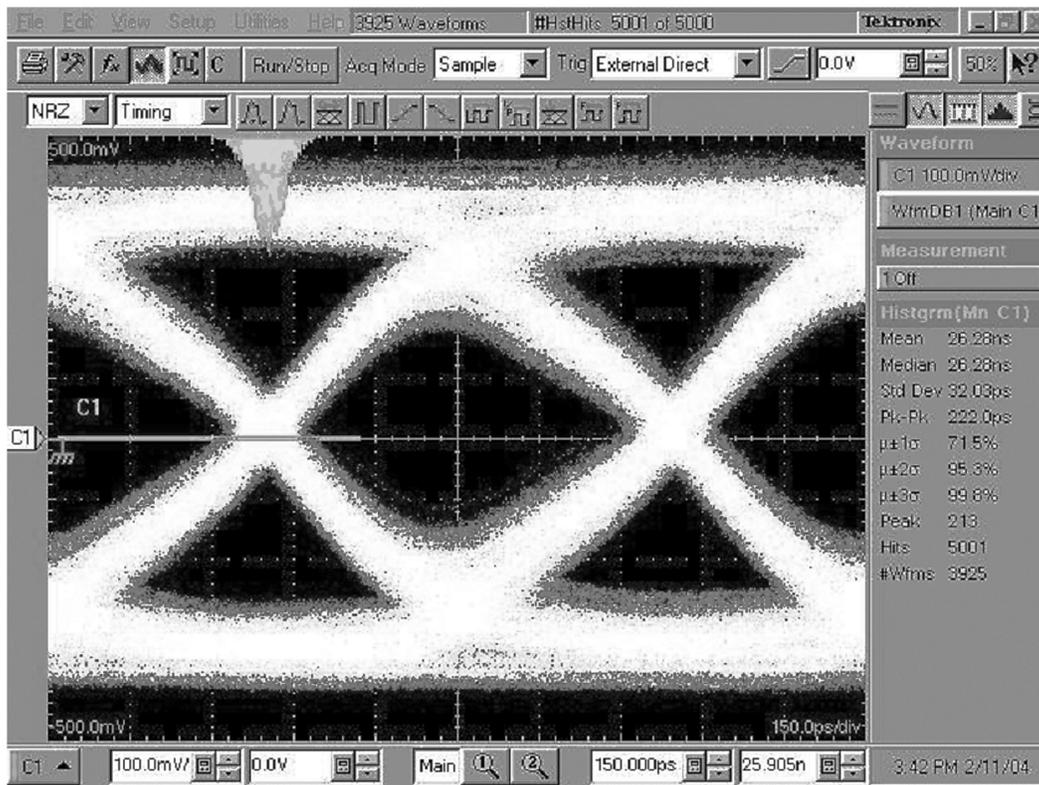
#### 4.2 External SerDes With Pre-Emphasis Feature

Even at the lower data rates used in parallel architectures, a factor limiting transmission distance has always been the electrical losses of the transmission media. Serial architectures have progressed to address the dielectric and skin effect loss issues associated with high-speed design in several ways. In order to achieve high-speed reliable data transmission across cables up to 50 feet long something must be done to compensate for the high frequency loss in the cable. Pre-emphasis is a circuit design technique that adds high frequency energy to the transmitter output signal, negating the loss incurred during data transmission across the medium. The Texas Instruments SCAN921821, a dual 18-bit Serializer, uses 6 dB of pre-emphasis to maintain robust, error-free communication across 50 feet of cable. This added feature increases the reach of LVDS SerDes by up to 5x at >1 Gbps serial data rates.



Measured after 15m of Infiniband Cable at the Input of the DS92LV18 Receiver;  $f_{\text{CLK}} = 66 \text{ MHz}$  (1.32 Gbps); No Pre-emphasis

**Figure 11. Eye Diagram Measured after 15m of Infiniband Cable at the Input of the DS92LV18 Receiver;  $f_{\text{CLK}} = 66 \text{ MHz}$  (1.32 Gbps); No Pre-emphasis**



Measured after 15m of Infiniband Cable at the Input of the DS92LV18 Receiver;  $f_{TCLK} = 66$  MHz (1.32 Gbps); Max Pre-emphasis

**Figure 12. Eye Diagram Measured after 15m of Infiniband Cable at the Input of the DS92LV18 Receiver;  $f_{TCLK} = 66$  MHz (1.32 Gbps); Max Pre-emphasis**

The eye diagrams shown in [Figure 11](#) and [Figure 12](#) clearly show the value of pre-emphasis for driving cables up to 15 to 20 meters in length. A SCAN921821 Dual 18-bit Serializer is transmitting the data while a DS92LV18 SerDes is receiving the data.

## 5 Conclusion

Using a stand alone SerDes is an effective way to minimize device generated SSO noise in the FPGAs. The external SerDes device allows the used to program the FPGA with a minimum output drive. The minimum drive limits the noise generated by the FPGA due to reduced simultaneous switching currents. Reduced noise lowers the risk that adjacent analog components will become inadvertent victims of excessive digital noise.

In addition to the local noise reduction benefits shown in the application note, Using a stand alone SerDes function provides lower jitter, BER and longer drive capability resulting in better analog performance. External SerDes function may also allow lower cost solutions with performances comparable to the higher cost solutions.

Analog enhancements, such as pre-emphasis, have enabled even higher speeds and longer drive distances over lossy interconnect. This capability, achieved though low cost silicon upgrades can be used to extend the operational life and enhance the functionality of systems currently deployed in the field.

## 6 Resources and References

1. *DS92LV16 16-bit SerDes Design Guide* ([SNLA201](#))
2. *18-bit SerDes Design Guide (DS92LV18, SCAN921821)* ([SNLA202](#))
3. *DS92LV16 16-Bit Bus LVDS Serializer/Deserializer - 25 - 80 MHz* ([SNLS138](#))
4. *DS92LV18 18-Bit Bus LVDS Serializer/Deserializer - 15-66 MHz* ([SNLS156](#))
5. *Cyclone Device Handbook Volumes 1 & 2*, Altera, 2003 and 2004, [www.altera.com](http://www.altera.com)
6. *Quartus II Handbook Volumes 1, 2 & 3*, Altera, 2004, [www.altera.com](http://www.altera.com)

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Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
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